

New Product

Si7485DP

Vishay Siliconix

P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)		
- 20	0.0073 at $V_{GS} = -4.5 V$	- 20		
	0.0090 at $V_{GS} = -2.5 \text{ V}$	– 18		
	0.013 at $V_{GS} = -1.8 V$	– 15		



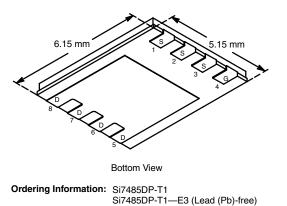


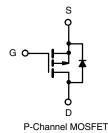
- TrenchFET[®] Power MOSFET
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07-mm Profile

APPLICATIONS

Battery Switch for Portable Devices







ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unles	ss otherwise r	noted		
Parameter	Symbol	10 secs	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 20		V
Gate-Source Voltage		V _{GS}	± 8		v
Continuous Drain Current (T 150 °C) ^a	T _A = 25 °C	I _D	- 20	- 12.5	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		- 16.5	- 9.5	А
Pulsed Drain Current		I _{DM}	- 50		~
Continuous Source Current (Diode Conduction) ^a		ا _S	- 4.5	- 1.6	
Mauinum Daura Diagingtiant	T _A = 25 °C	P _D	5	1.8	W
Maximum Power Dissipation ^a	T _A = 70 °C		3.2	1.1	vv
Operating Junction and Storage Temperature Range		T _J , T _{stg}	– 55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{b,c}			260		C

THERMAL RESISTANCE BATINGS

Parameter		Symbol	Typical	Maximum	Unit
Movinum lunction to Ambienta	$t \le 10 \text{ sec}$	R _{thJA}	20	25	
Maximum Junction-to-Ambient ^a	Steady State		54	68	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.7	2.2	

Notes

a. Surface Mounted on 1" x 1" FR4 Board.

b. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection. c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

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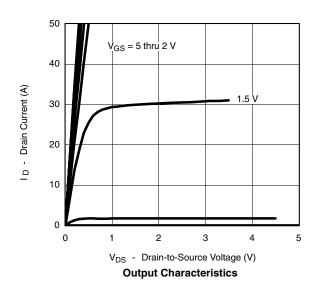


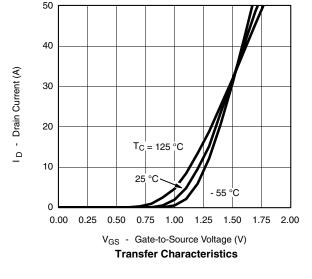
SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted								
Parameter	Symbol	Test Condition	Min	Тур	Мах	Unit		
Static								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -1 \text{ mA}$	- 0.4		- 0.9	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 8 V$			± 100	nA		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			- 1			
		$V_{DS} = -20 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 70 ^{\circ}\text{C}$			- 10	μA		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -5$ V, $V_{GS} = -4.5$ V	- 40			А		
Drain-Source On-State Resistance ^a		$V_{GS} = -4.5$ V, $I_{D} = -20$ A	0.006 0.0073					
	r _{DS(on)}	$V_{GS} = -2.5 \text{ V}, \text{ I}_{D} = -18 \text{ A}$		0.0074	0.0090	Ω		
		$V_{GS} = -1.8$ V, $I_{D} = -15$ A		0.0106	0.013			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, \text{ I}_{D} = -20 \text{ A}$		80		S		
Diode Forward Voltage ^a	V _{SD}	$I_{S} = -4.5 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.62	- 1.1	V		
Dynamic ^b								
Total Gate Charge	Qg			99	150			
Gate-Source Charge	Q _{gs}	$V_{DS} = -10$ V, $V_{GS} = -5$ V, $I_{D} = -20$ A		11.5		nC		
Gate-Drain Charge	Q _{gd}			29				
Gate Resistance	Rg			2.4		Ω		
Turn-On Delay Time	t _{d(on)}			80	120			
Rise Time	t _r	V_{DD} = $-$ 10 V, R_L = 10 Ω		140	210			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -$ 1 A, V_{GEN} = $-$ 4.5 V, R_G = 6 Ω		360	540	ns		
Fall Time	t _f			170	260			
Source-Drain Reverse Recovery Time	t _{rr}	I _F = – 2.9 A, di/dt = 100 A/μs		55	80			

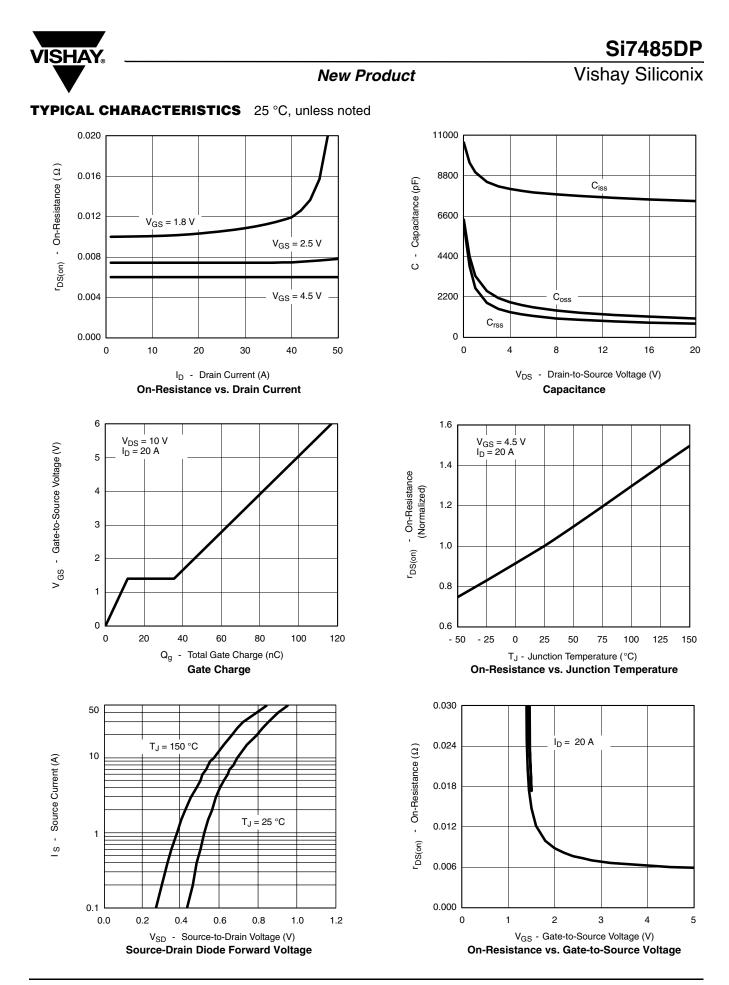
Notes a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless noted



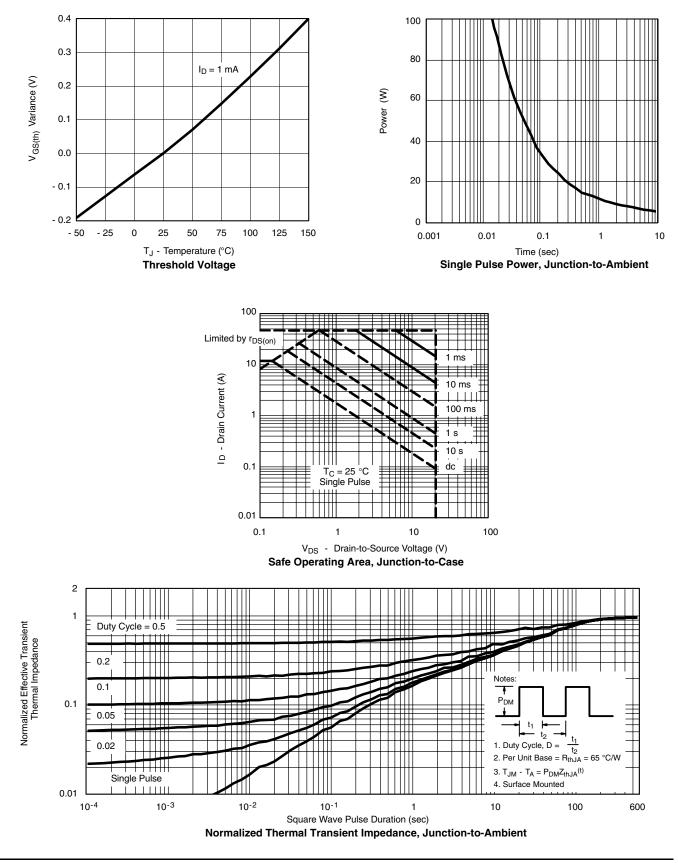




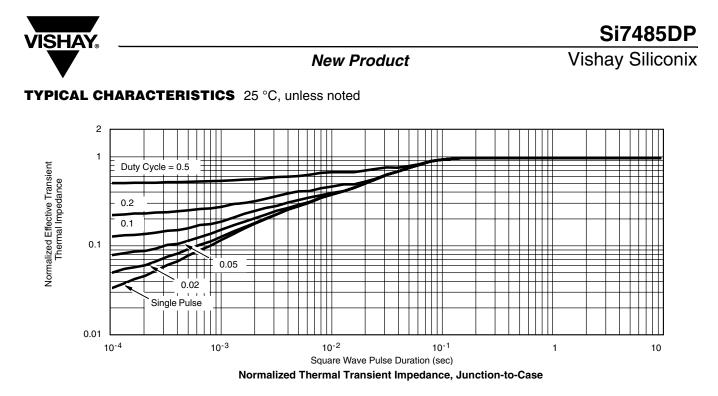
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New Product





VISHA



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72275.



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